

Material Composition Data

Product: GTXO-93

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Timing Is Everything

GTXO-93 - 1.8V ~ 3.6V SM (VC)TCXO for GPS

Sub-Assembly	Material	Substance	CAS No	Mass (mg)	Sub-Assembly % by mass
Base 1	Ceramic	Al ₂ O ₃	1344-28-1	10.249	74.27
		W	7440-33-7	1.795	13.01
		Ni	7440-02-0	0.638	4.62
		SiO ₂	14808-60-7	0.501	3.63
		Mo	7439-98-7	0.160	1.16
		Co	7440-48-4	0.159	1.15
		Au	7440-57-5	0.080	0.58
		Cr ₂ O ₃ *	1308-38-9	0.077	0.56
		CaO	1305-78-8	0.073	0.53
		MgO	1309-48-4	0.068	0.49
Base 2		Al ₂ O ₃	1344-28-1	10.260	71.75
		W	7440-33-7	2.111	14.76
		Ni	7440-02-0	0.749	5.24
		SiO ₂	14808-60-7	0.501	3.50
		Co	7440-48-4	0.190	1.33
		Mo	7439-98-7	0.170	1.19
		Au	7440-57-5	0.099	0.69
		Cr ₂ O ₃ *	1308-38-9	0.080	0.56
		CaO	1305-78-8	0.070	0.49
		MgO	1309-48-4	0.070	0.49
Lid	Kovar (Fe/Ni/Co alloy lid)	Fe	7439-89-6	1.960	49.25
		Ni	7440-02-0	1.070	26.88
		Co	7440-48-4	0.620	15.58
		Ni	7440-02-0	0.280	7.04
		Mn	7439-96-5	0.020	0.50
		C	7440-44-0	0.020	0.50
		Si	7440-21-3	0.010	0.25
Blank	SiO ₂	SiO ₂	14808-60-7	0.300	100.00
IC	Wafer Chip (Die)	Si	7440-21-3	0.797	99.63
		Al	7429-90-5	0.003	0.38
		Cu	7440-50-8	0.000	0.00
		As	1344-28-1	0.000	0.00
		P	7723-14-0	0.000	0.00
		B	7440-42-8	0.000	0.00

Total Mass: 33.180 mg

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